

SOT1945-1

VFBGA180, plastic, very thin fine pitch ball grid array; 180 bumps; 0.5 mm pitch; 8 mm x 8 mm x 0.86 mm body

12 October 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA180
Package type industry code	VFBGA180
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-10-2017
Manufacturer package code	SOT1945-1

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	8	-	mm
E	package width	-	-	8	-	mm
A	seated height	-	-	0.86	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	180	-	A/A



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2. Package outline

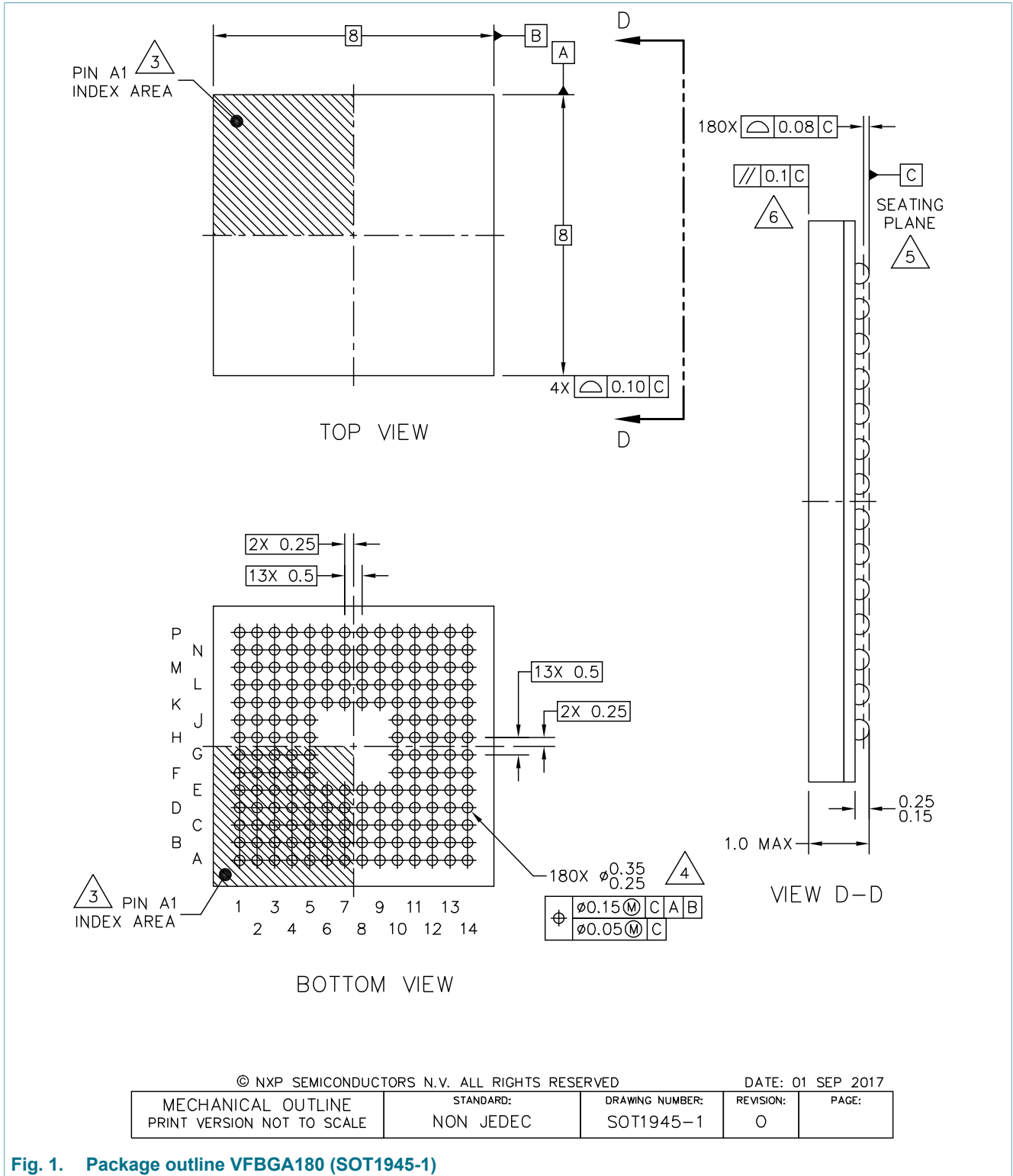


Fig. 1. Package outline VFBGA180 (SOT1945-1)

VFBGA180, plastic, very thin fine pitch ball grid array; 180 bumps; 0.5 mm pitch; 8 mm x 8 mm x 0.86 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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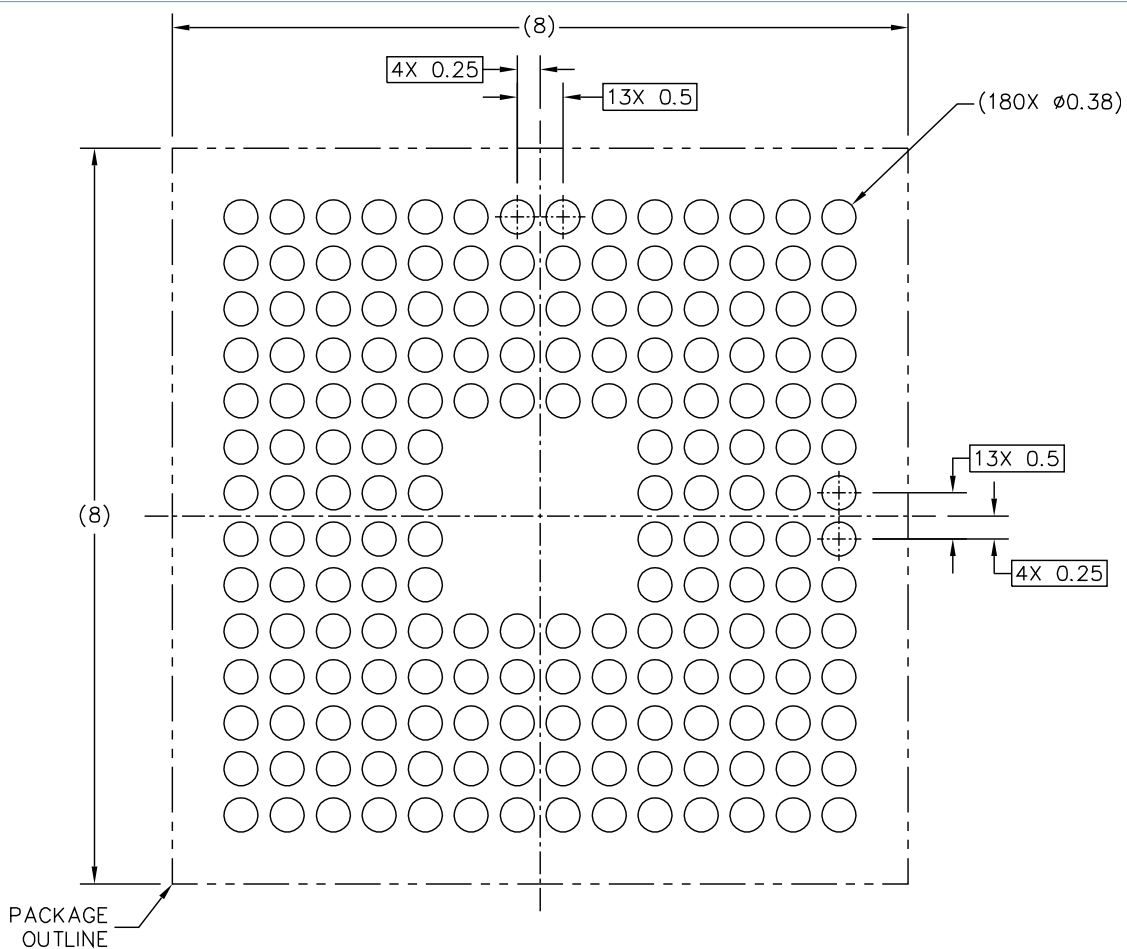
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Fig. 2. Package outline note VFBGA180 (SOT1945-1)

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3. Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

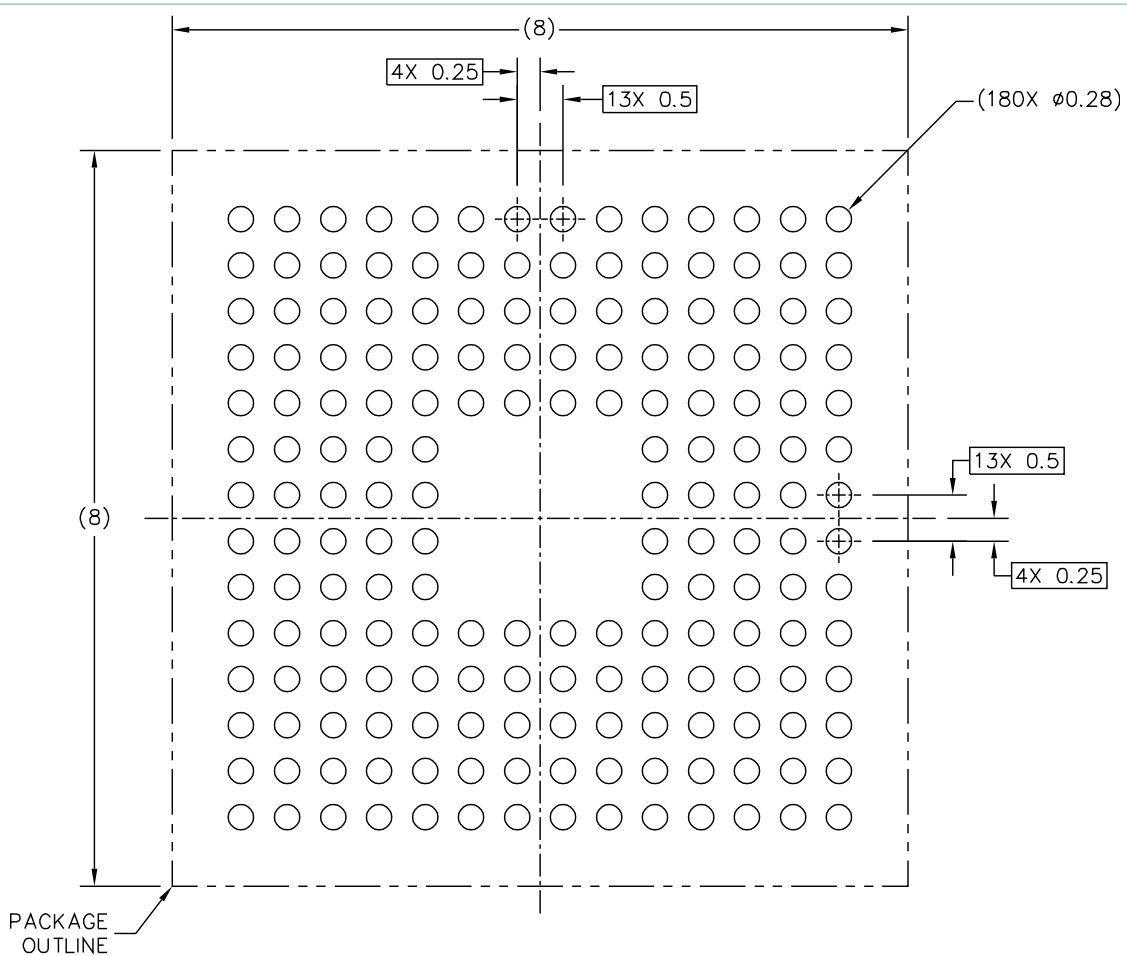
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Fig. 3. Reflow soldering footprint for VFBGA180 (SOT1945-1)

VFBGA180, plastic, very thin fine pitch ball grid array; 180 bumps; 0.5 mm pitch; 8 mm x 8 mm x 0.86 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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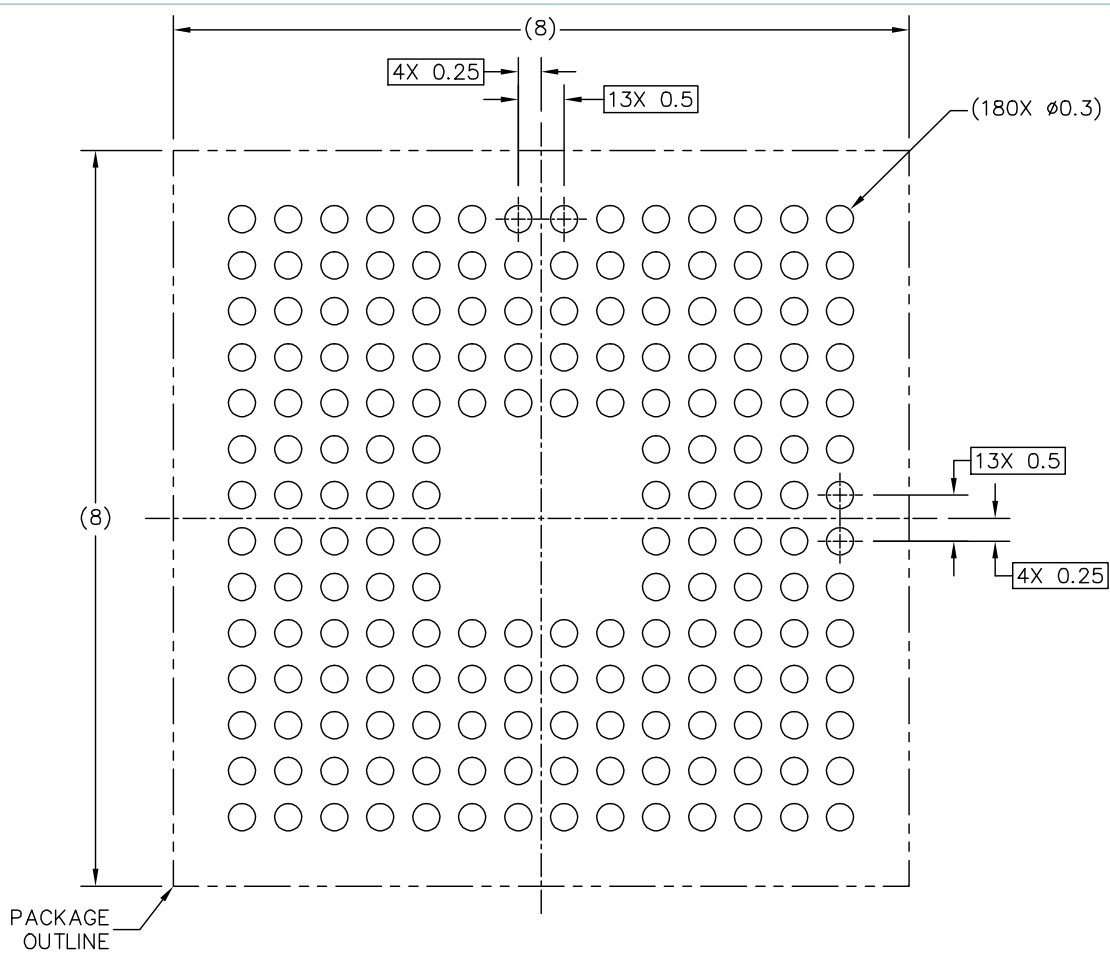
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Fig. 4. Reflow soldering footprint part2 for VFBGA180 (SOT1945-1)

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 5. Reflow soldering footprint part3 for VFBGA180 (SOT1945-1)

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4. Legal information

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